

L Number	Hits	Search Text	DB	Time stamp
1	786	((438/666) or (438/667)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/30 00:31
2	1	((438/666) or (438/667)).CCLS.) and micropore	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/30 00:32
3	335	((438/666) or (438/667)).CCLS.) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/30 00:33
4	172	((438/666) or (438/667)).CCLS.) and (bond\$3 near5 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/30 00:33
5	115	((438/666) or (438/667)).CCLS.) and (bond\$3 near5 pad) and (bond\$3 near10 (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/30 00:34